

Appl. No. 10/711,794
Amdt. dated July 12, 2006
Reply to Office action of June 16, 2006

Amendments to the Claims:

Listing of Claims:

Claim 1 (previously presented): A package structure comprising:

- 5 a lead frame having a plurality of leads, which includes a first recession and a
 second recession;
 at least a semiconductor chip;
 a plurality of first solder joints respectively positioned in the first recessions for
 connecting the semiconductor chip to the lead frame;
10 at least one passive device having a plurality of outputs respectively positioned in
 the second recessions; and
 a plurality of second solder joints respectively positioned in the second recessions
 for connecting the passive device to the lead frame.

Claim 2 (cancelled)

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Claim 3 (cancelled)

Claim 4 (previously presented): The package structure of claim 1 wherein the passive
device is an electrical resistor, a capacitor, or an inductor.

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Claim 5 (cancelled)

Claim 6 (cancelled)

25 Claim 7 (cancelled)

Claim 8 (cancelled)

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Claim 9 (previously presented): The package structure of claim 1 wherein the second solder joints are comprised of tin or tin alloy.

5 Claim 10 (previously presented): The package structure of claim 1 wherein the lead frame comprises a die pad connected to the semiconductor chip for radiating the heat produced by the semiconductor chip by serving as a heat sink.

10 Claim 11 (previously presented): The package structure of claim 10 wherein the die pad comprises a ground pad connected to both ground and the semiconductor chip.

Claim 12 (previously presented): The package structure of claim 1 wherein the first solder joints are comprised of tin or tin alloy.

15 Claim 13 (cancelled)

Claim 14 (cancelled)

Claim 15 (cancelled)

20 Claim 16 (cancelled)